	Application No.	Applicant(s)	
Notice of Allowability	10/735,886	TAKAYAMA ET AL.	
	Examiner	Art Unit	
	Nitin Parekh	2811	
The MAILING DATE of this communication appeal claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT R of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this application or other appropriate communication IGHTS. This application is subject to	olication. If not include will be mailed in due c	d course. THIS
1. This communication is responsive to <u>4-24-06</u> .			
2. \boxtimes The allowed claim(s) is/are <u>1,4-6 and 18</u> .			
3. Acknowledgment is made of a claim for foreign priority una) All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority do International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 4. A SUBSTITUTE OATH OR DECLARATION must be subm INFORMAL PATENT APPLICATION (PTO-152) which giv 5. CORRECTED DRAWINGS (as "replacement sheets") mu (a) including changes required by the Notice of Draftsper 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in 6. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT	e been received. e been received in Application No becoments have been received in this of this communication to file a reply MENT of this application. Initted. Note the attached EXAMINER res reason(s) why the oath or declara st be submitted. son's Patent Drawing Review (PTO 's Amendment / Comment or in the Comment or in the Comment of the drawithe header according to 37 CFR 1.121(Dosit of BIOLOGICAL MATERIAL	national stage application of the following in the front (not the (d).	uirements OTICE OF
Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SB/Paper No./Mail Date 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	Paper No./Mail Da /08), 7. ⊠ Examiner's Amend	(PTO-413), ate ment/Comment	owance

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DETAILED ACTION

Allowable Subject Matter

1. Claims 1, 4-6 and 18 are allowed.

Claims 7-17, non-elected without traverse, have been cancelled.

Examiner's Amendment

- 2. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.
- A. Claim 1, line 4: Delete "trench" and insert --- "hole" ---.
- B. Claim 1, line 9: Insert --- "said hole" --- between "hole" and "so".
- C. Claim 18, line 7: Delete "trench" and insert --- "hole" ---.
- D. Claim 18, line 12: Insert --- "said hole" --- between "hole" and "so".

Authorization for this examiner's amendment was given in a telephone interview with Darren Crew on 6-21-06.

Reasons for Allowance

3. The following is an examiner's statement of reasons for allowance:

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The references of record do not teach either singularly or in combination at least the limitations "said copper interconnection pattern having a top principal surface coincident to a top principal surface of said first interconnection laver and filling a hole formed in said first interconnection laver" and "a via-hole formed in said interlayer insulation film so as to expose said copper interconnection pattern", "wherein there is formed a conductive nitride film between an outer wall of said tungsten plug and an inner wall of said via-hole" and "said conductive nitride film being formed of a first nitride film and a second nitride film stacked inside said first nitride film" in a multilayer interconnection structure having copper interconnect wiring and tungsten filled via holes.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nitin Parekh whose telephone number is 571-272-1663. The examiner can normally be reached on 09:00AM-05:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie Lee can be reached on 571-272-1732. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAN or Public PAG. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAG system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

Nitin Parekh

PRIMARY EAMINER

NP

TECHNOLOGY CENTER 2800

06-21-06